

Thin Wafers Temporary Bonding Equipment and Materials Market, Global Outlook and Forecast 2022-2028

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Abstracts

Thin wafer handling will enjoy increased importance in the coming years, but as chips get thinner and wafer diameter increases, thinning/handling procedures are required. This implies development in wafer thinning, wafer dicing and wafer temporary bonding. Temporary bonding implies know-how in process and chemistry, and an understanding of the final application requirements. Temporary bonding is a complex technology, requiring an interface material (sometimes called the "Magic" material) that is strong enough to withstand post-processing but which can be easily removed afterwards. As the main concern for temporary bonding materials (wax, tape or glue) is temperature stability, the material must be strong enough to withstand processing steps (metallization, etching, grinding). Another issue is the choice of carrier material. Carrier lifetime depends on its capability to withstand steps such as grinding, etc., and carrier lifetime should be at least tens of times.

This report contains market size and forecasts of Thin Wafers Temporary Bonding Equipment and Materials in Global, including the following market information:

Global Thin Wafers Temporary Bonding Equipment and Materials Market Revenue, 2017-2022, 2023-2028, (\$ millions)

Global top five companies in 2021 (%)

The global Thin Wafers Temporary Bonding Equipment and Materials market was valued at million in 2021 and is projected to reach US\$ million by 2028, at a CAGR of % during the forecast period.



The U.S. Market is Estimated at \$ Million in 2021, While China is Forecast to Reach \$ Million by 2028.

Chemical Debonding Segment to Reach \$ Million by 2028, with a % CAGR in next six years.

The global key manufacturers of Thin Wafers Temporary Bonding Equipment and Materials include 3M, ABB, Accretech, AGC, AMD, Cabot, Corning, Crystal Solar and Dalsa, etc. In 2021, the global top five players have a share approximately % in terms of revenue.

MARKET MONITOR GLOBAL, INC (MMG) has surveyed the Thin Wafers Temporary Bonding Equipment and Materials companies, and industry experts on this industry, involving the revenue, demand, product type, recent developments and plans, industry trends, drivers, challenges, obstacles, and potential risks.

Total Market by Segment:

Global Thin Wafers Temporary Bonding Equipment and Materials Market, by Type, 2017-2022, 2023-2028 (\$ millions)

Global Thin Wafers Temporary Bonding Equipment and Materials Market Segment Percentages, by Type, 2021 (%)

Chemical Debonding

Hot Sliding Debonding

Mechanical Debonding

Laser Debonding

Global Thin Wafers Temporary Bonding Equipment and Materials Market, by Application, 2017-2022, 2023-2028 (\$ millions)

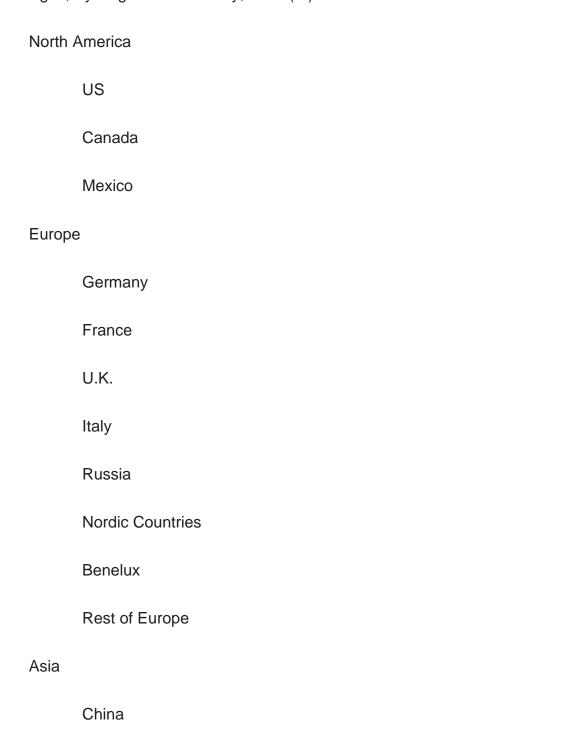
Global Thin Wafers Temporary Bonding Equipment and Materials Market Segment Percentages, by Application, 2021 (%)



below 40µm Wafers

Global Thin Wafers Temporary Bonding Equipment and Materials Market, By Region and Country, 2017-2022, 2023-2028 (\$ Millions)

Global Thin Wafers Temporary Bonding Equipment and Materials Market Segment Percentages, By Region and Country, 2021 (%)





Japan		
South Korea		
Southeast Asia		
India		
Rest of Asia		
South America		
Brazil		
Argentina		
Rest of South America		
Middle East & Africa		
Turkey		
Israel		
Saudi Arabia		
UAE		
Rest of Middle East & Africa		
Competitor Analysis		
The report also provides analysis of leading market participants including:		

Key companies Thin Wafers Temporary Bonding Equipment and Materials revenues

Key companies Thin Wafers Temporary Bonding Equipment and Materials revenues in

global market, 2017-2022 (estimated), (\$ millions)



share in global market, 2021 (%)

Further, the report presents profiles of competitors in the market, key players include:	
3M	
ABB	
Accretech	
AGC	
AMD	
Cabot	
Corning	
Crystal Solar	
Dalsa	
DoubleCheck Semiconductors	
1366 Technologies	
Ebara	
ERS	
Hamamatsu	
IBM	
Intel	
LG Innotek	

Mitsubishi Electric



Qualcomm	

Robert Bosch

Samsung

Sumitomo Chemical



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